



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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## Product Summary

$BV_{DSS}$	Max $R_{DS(ON)}$	Max $I_D$ $T_A = +25^\circ C$
-450V	150 $\Omega$ @ $V_{GS} = -10V$	-75mA

## Features and Benefits

- 450 Volt  $V_{DS}$
- $R_{DS(ON)} = 150\Omega$

## Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance ( $R_{DS(ON)}$ ) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- High-voltage power MOSFET drivers

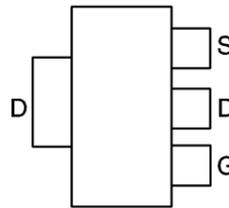
## Mechanical Data

- Package: SOT223
- Package Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.112 grams (Approximate)

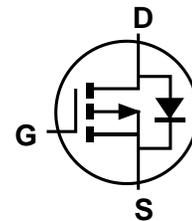
SOT223 (Type DN)



Top View



Pinout - Top View



Equivalent Circuit

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	-450	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-75	mA
Pulsed Drain Current	$I_{DM}$	-150	mA

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation	$P_D$	2	W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	-450	—	—	V	$V_{GS} = 0V, I_D = 1mA$
Zero Gate Voltage Drain Current ( $T_J = +25^\circ\text{C}$ )	$I_{DSS}$	—	—	-20 -2	$\mu\text{A}$ mA	$V_{DS} = -450V, V_{GS} = 0V$ $V_{DS} = -360V, V_{GS} = 0V,$ $T_A = +125^\circ\text{C}$ (Note 6)
Gate-Source Leakage	$I_{GSS}$	—	—	20	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
On-State Drain Current (Note 5)	$I_{D(ON)}$	-100	—	—	mA	$V_{GS} = -10V, V_{DS} = -25V$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	-1.5	—	-4.5	V	$V_{DS} = V_{GS}, I_D = -1mA$
Static Drain-Source On-Resistance (Note 5)	$R_{DS(ON)}$	—	—	150	$\Omega$	$V_{GS} = -10V, I_D = -50mA$
Forward Transconductance (Note 5) (Note 6)	$g_{fs}$	40	—	—	mS	$V_{DS} = -25V, I_D = -50mA$
<b>DYNAMIC CHARACTERISTICS (Note 6)</b>						
Input Capacitance	$C_{iss}$	—	—	120	pF	$V_{DS} = -25V, V_{GS} = 0V, f = 1.0MHz$
Output Capacitance	$C_{oss}$	—	—	20	pF	
Reverse Transfer Capacitance	$C_{rss}$	—	—	5	pF	
Turn-On Delay Time (Note 7)	$t_{D(ON)}$	—	—	10	ns	$V_{DD} = -25V, I_D = -50mA$
Turn-On Rise Time (Note 7)	$t_r$	—	—	15	ns	
Turn-Off Delay Time (Note 7)	$t_{D(OFF)}$	—	—	15	ns	
Turn-Off Fall Time (Note 7)	$t_f$	—	—	20	ns	

- Notes:
5. Measured under pulsed conditions. Width=300 $\mu\text{s}$ . Duty cycle  $\leq 2\%$ .
  6. Sample test.
  7. Switching times measured with 50 $\Omega$  source impedance and <5ns rise time on a pulse generator.

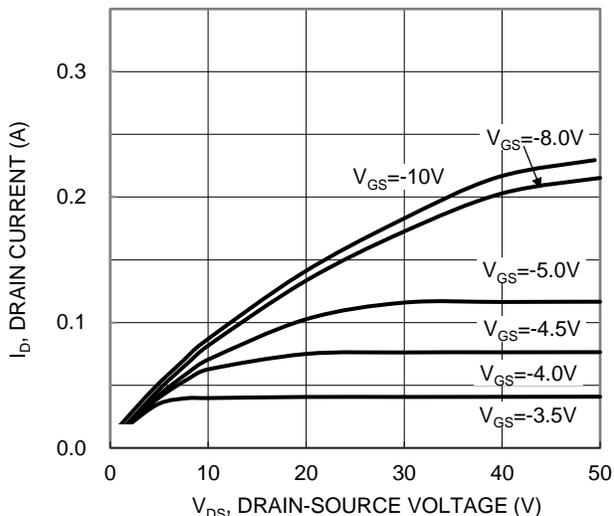


Figure 1. Typical Output Characteristic

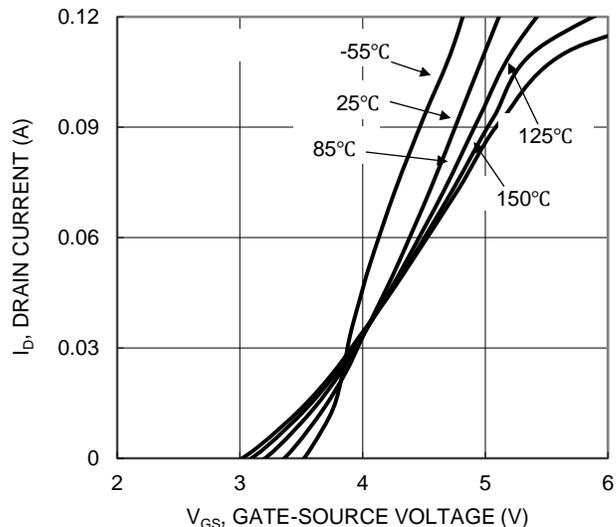


Figure 2. Typical Transfer Characteristic

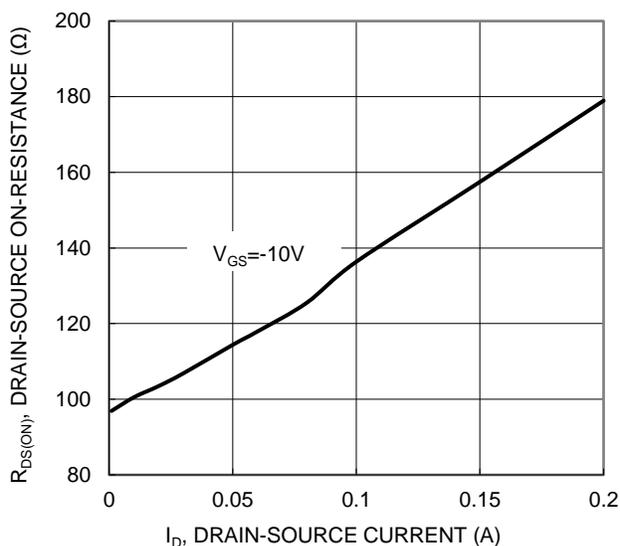


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

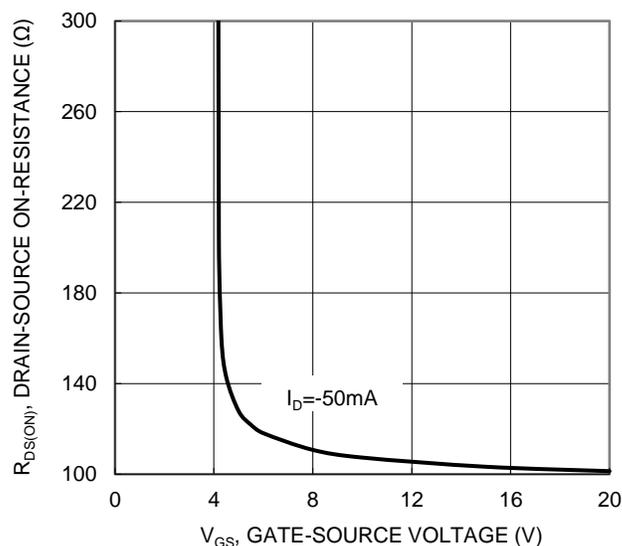


Figure 4. Typical Transfer Characteristic

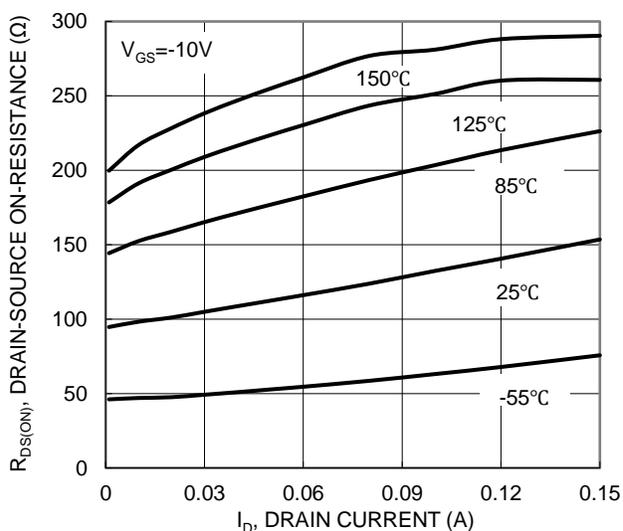


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

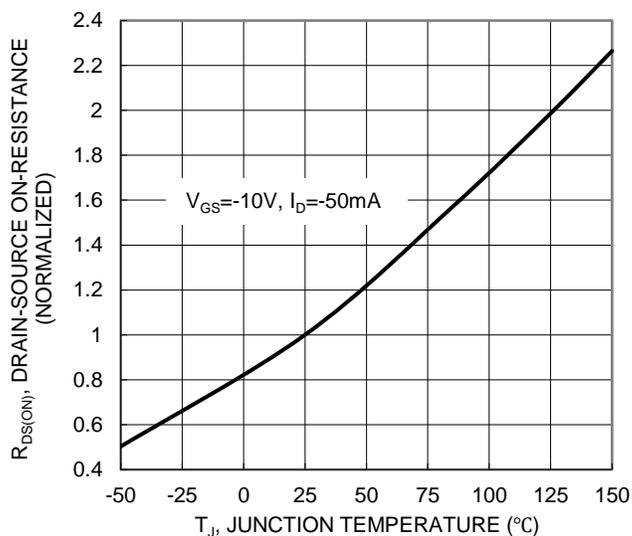
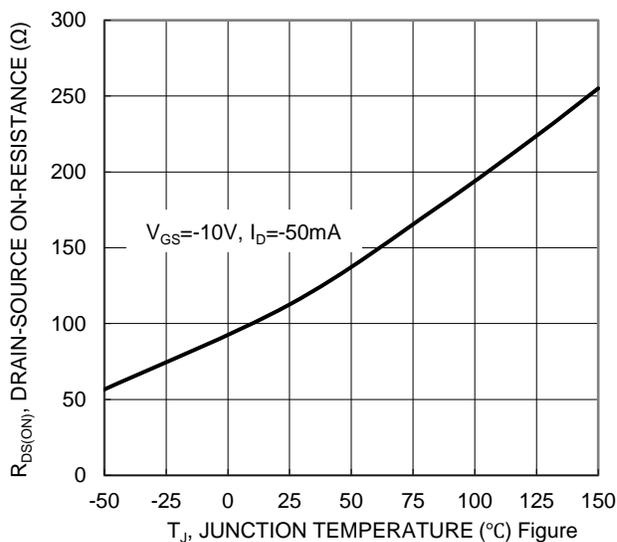


Figure 6. On-Resistance Variation with Junction Temperature



7. On-Resistance Variation with Junction Temperature

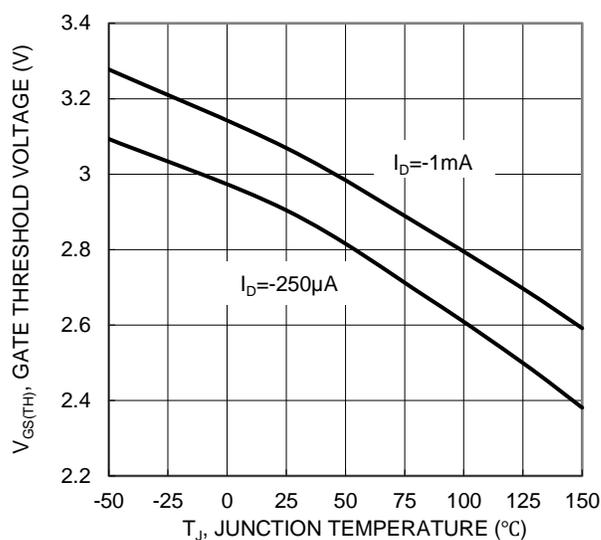


Figure 8. Gate Threshold Variation vs Junction Temperature

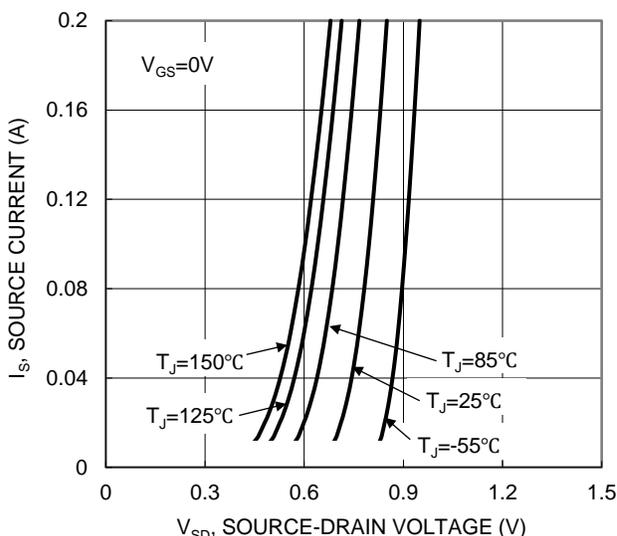


Figure 9. Diode Forward Voltage vs Current

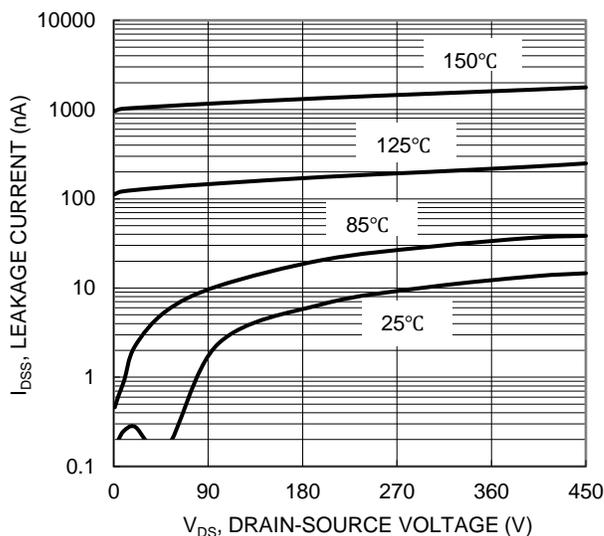


Figure 10. Typical Drain-Source Leakage Current vs

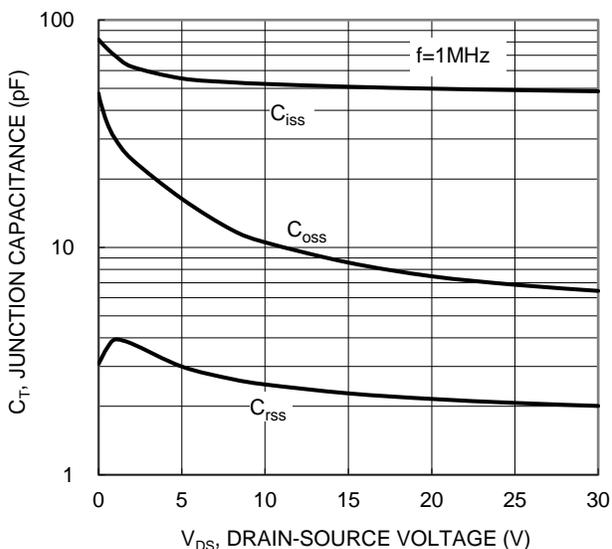


Figure 11. Typical Junction Capacitance

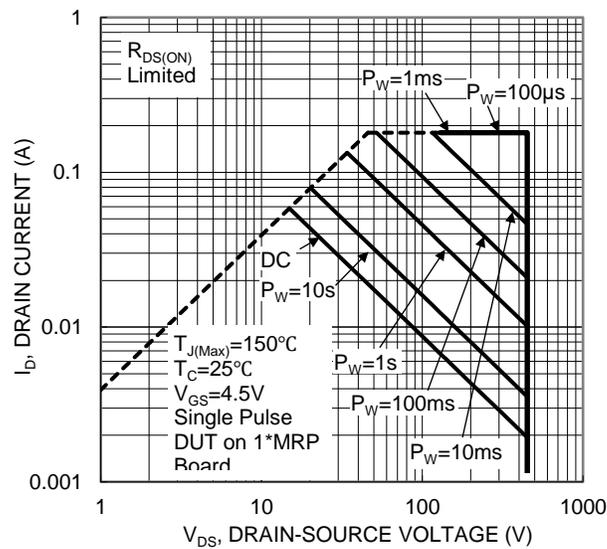


Figure 12. SOA, Safe Operation Area

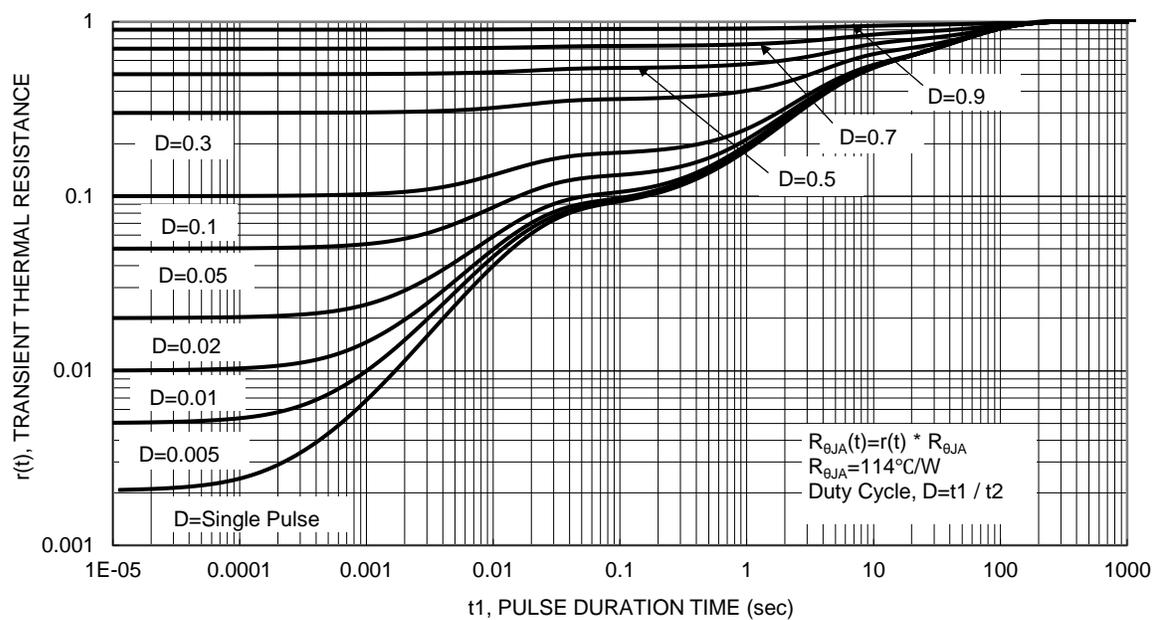
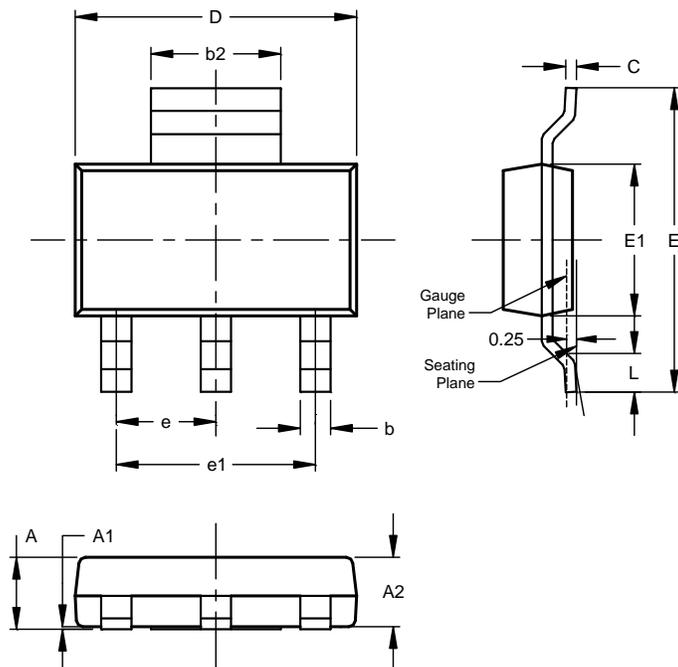


Figure 13. Transient Thermal Resistance

## Package Outline Dimensions

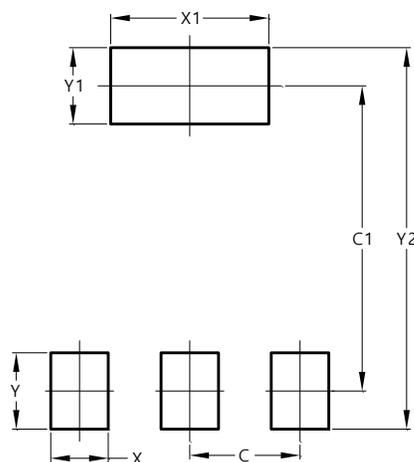
SOT223 (Type DN)



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Dim	Min	Max	Typ
A	--	1.70	--
A1	0.01	0.15	--
A2	1.50	1.68	1.60
b	0.60	0.80	0.70
b2	2.90	3.10	--
c	0.20	0.32	--
D	6.30	6.70	--
E	6.70	7.30	--
E1	3.30	3.70	--
e	--	--	2.30
e1	--	--	4.60
L	0.85	--	--
All Dimensions in mm			

## Suggested Pad Layout

SOT223 (Type DN)



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00